IGBT - Power, Single, N-Channel, Field Stop VII (FS7), SCR, Power TO247-4L
1200 V, 1.45 V, 40 A

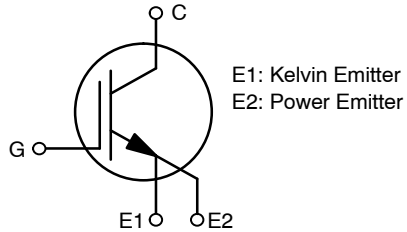
AFGH4L40T120RW

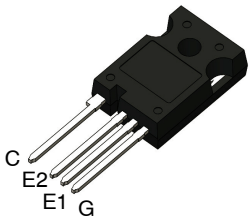
BV_{CES}	$VCE_{(sat)}$ TYP	I_C MAX
1200 V	1.45 V	40 A

Description
Using the novel field stop 7th generation IGBT technology in TO247 4−lead package, this device offers the optimum performance with low on state voltage and minimal switching losses for both hard and soft switching topologies in automotive applications.

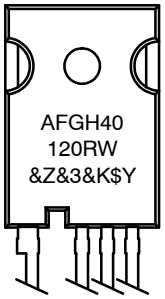
Features
- Extremely Efficient Trench with Field Stop Technology
- Maximum Junction Temperature − T_J = 175°C
- Short Circuit Rated and Low Saturation Voltage
- Fast Switching and Tightened Parameter Distribution
- AEC−Q101 Qualified, PPAP Available Upon Request
- These Device is Pb−Free, Halogen Free/BFR Free and is RoHS Compliant

Applications
- Automotive E−compressor
- Automotive EV PTC Heater
- OBC

PIN CONNECTIONS




TO−247−4LD
CASE 340CJ

MARKING DIAGRAM


AFGH40120RW	= Specific Device Code
&Z	= Assembly Plant Code
&3	= 3−Digit Date Code
&K	= 2−Digit Lot Traceability Code
$Y	= **onsemi** Logo

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter		Symbol	Value	Unit
Collector to Emitter Voltage		V_{CE}	1200	V
Gate to Emitter Voltage		V_{GE}	±20	
Transient Gate to Emitter Voltage			±30	
Collector Current	T_C = 25°C	I_C	80	A
	T_C = 100°C		40	
Power Dissipation	T_C = 25°C	P_D	576	W
	T_C = 100°C		288	
Pulsed Collector Current	T_C = 25°C, t_p = 10 μs (Note 1)	I_{CM}	120	A
Short Circuit Withstand Time V_{GE} = 15 V, Vcc = 800 V, T_C = 150°C		T_{SC}	6	μs
Operating Junction and Storage Temperature Range		T_J, T_{stg}	−55 to +175	°C
Lead Temperature for Soldering Purposes		T_L	260	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. Repetitive rating: Pulse width limited by max. junction temperature

ORDERING INFORMATION

Device	Package	Shipping
AFGH4L40T120RW	TO−247−4L (Pb−Free)	30 Units / Rail

© Semiconductor Components Industries, LLC, 2023

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction−to−Case for IGBT	$R_{\theta JC}$	0.26	°C/W
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	40	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Collector to Emitter Breakdown Voltage	BV_{CES}	V_{GE} = 0 V, I_C = 1 mA	1200	–	–	V
Zero Gate Voltage Collector Current	I_{CES}	V_{GE} = 0 V, V_{CE} = V_{CES}	–	–	40	μA
Gate−to−Emitter leakage Current	I_{GES}	V_{GE} = ±20 V, V_{CE} = 0 V	–	–	±400	nA
ON CHARACTERISTICS						
Gate to Emitter Threshold Voltage	$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 40 mA, T_J = 25°C	4.98	5.88	6.78	V
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	V_{GE} = 15 V, I_C = 40 A, T_J = 25°C	–	1.45	1.78	V
		V_{GE} = 15 V, I_C = 40 A, T_J = 175°C	–	1.75	–	
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{IES}	V_{CE} = 30 V, V_{GE} = 0 V, f = 1 MHz	–	4721	–	pF
Output Capacitance	C_{OES}		–	144	–	pF
Reverse Transfer Capacitance	C_{RES}		–	24.2	–	pF
Total Gate Charge	Q_G	V_{CE} = 600 V, V_{GE} = 15 V, I_C = 40 A	–	171	–	nC
Gate to Emitter Charge	Q_{GE}		–	42.2	–	nC
Gate to Collector Charge	Q_{GC}		–	73.4	–	nC
SWITCHING CHARACTERISTICS, INDUCTIVE LOAD (Note: Si Diode Applied)						
Turn−On Delay Time	$t_{d(on)}$	V_{CE} = 600 V V_{GE} = 0/15 V I_C = 20 A R_G = 6 Ω T_J = 25°C	–	53.5	–	ns
Turn−Off Delay Time	$t_{d(off)}$		–	311	–	
Rise Time	t_r		–	27.8	–	
Fall Time	t_f		–	189	–	
Turn−On Switching Loss	E_{on}		–	1.26	–	mJ
Turn−Off Switching Loss	E_{off}		–	1.36	–	
Total Switching Loss	E_{ts}		–	2.61	–	
Turn−On Delay Time	$t_{d(on)}$	V_{CE} = 600 V V_{GE} = 0/15 V I_C = 40 A R_G = 6 Ω T_J = 25°C	–	58.2	–	ns
Turn−Off Delay Time	$t_{d(off)}$		–	258	–	
Rise time	t_r		–	47.4	–	
Fall Time	t_f		–	122	–	
Turn−On Switching Loss	E_{on}		–	3.38	–	mJ
Turn−Off Switching Loss	E_{off}		–	1.7	–	
Total Switching Loss	E_{ts}		–	5.08	–	

Share Feedback
Your Opinion Matters

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified) (continued)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
SWITCHING CHARACTERISTICS, INDUCTIVE LOAD (Note: Si Diode Applied)						
Turn−On Delay Time	$t_{d(on)}$	V_{CE} = 600 V V_{GE} = 0/15 V I_C = 20 A R_G = 6 Ω T_J = 175°C	–	58.7	–	ns
Turn−Off Delay Time	$t_{d(off)}$		–	433	–	
Rise Time	t_r		–	39.4	–	
Fall Time	t_f		–	376	–	
Turn−On Switching Loss	E_{on}		–	2.01	–	mJ
Turn−Off Switching Loss	E_{off}		–	2.52	–	
Total Switching Loss	E_{ts}		–	4.53	–	
Turn−On Delay Time	$t_{d(on)}$	V_{CE} = 600 V V_{GE} = 0/15 V I_C = 40 A R_G = 6 Ω T_J = 175°C	–	65.7	–	ns
Turn−Off Delay Time	$t_{d(off)}$		–	343	–	
Rise Time	t_r		–	64.7	–	
Fall Time	t_f		–	233	–	
Turn−On Switching Loss	E_{on}		–	5.45	–	mJ
Turn−Off Switching Loss	E_{off}		–	3.04	–	
Total Switching Loss	E_{ts}		–	8.49	–	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Share Feedback
Your Opinion Matters

TYPICAL CHARACTERISTICS

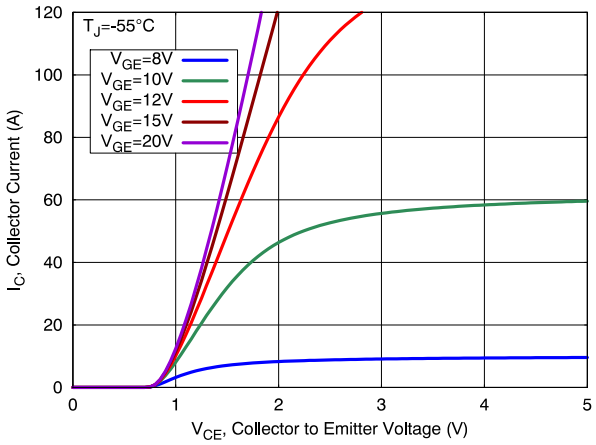


Figure 1. Output Characteristics

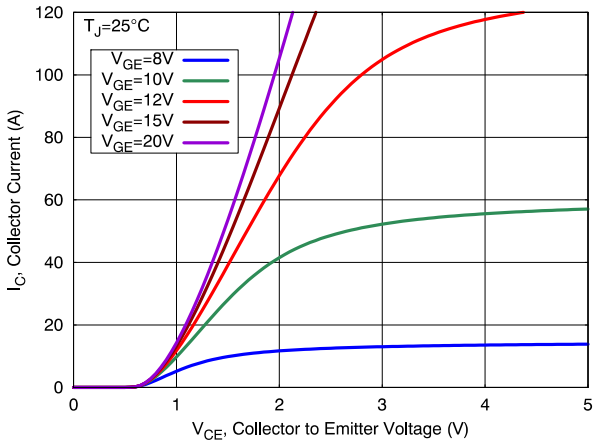


Figure 2. Output Characteristics

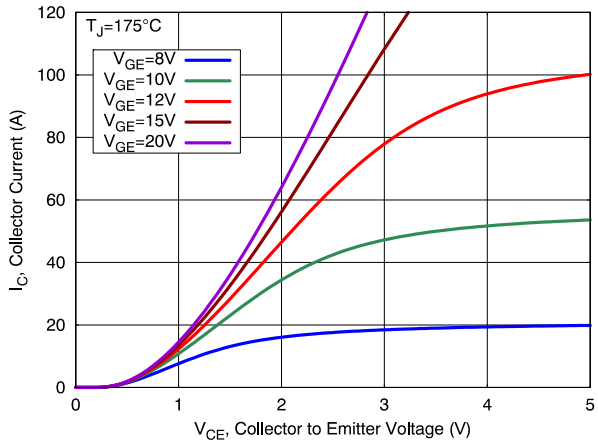


Figure 3. Output Characteristics

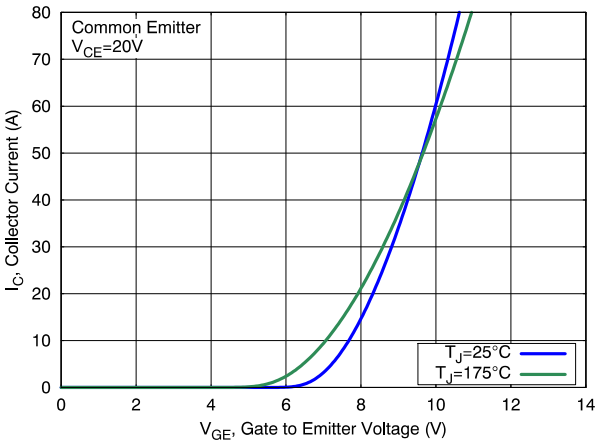


Figure 4. Transfer Characteristics

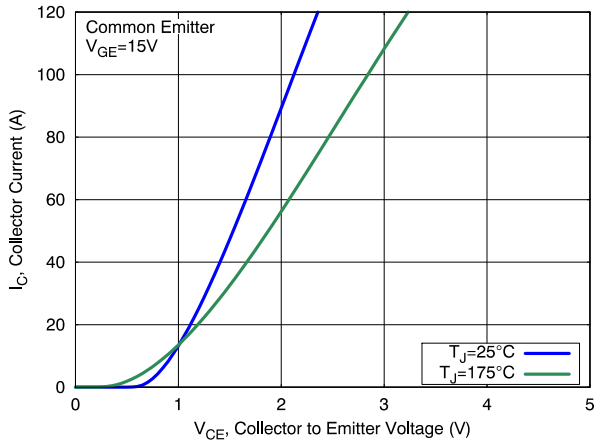


Figure 5. Saturation Characteristics

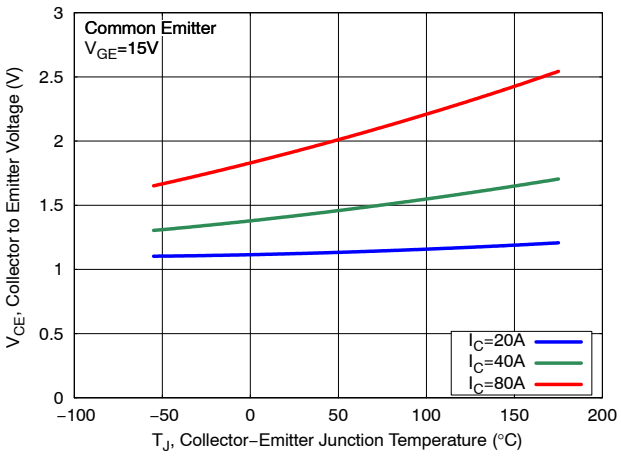


Figure 6. Saturation Voltage vs. Junction Temperature

Share Feedback
Your Opinion Matters

TYPICAL CHARACTERISTICS

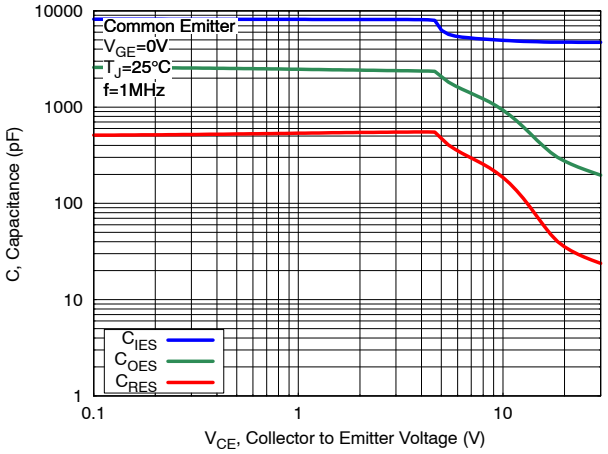


Figure 7. Capacitance Characteristics

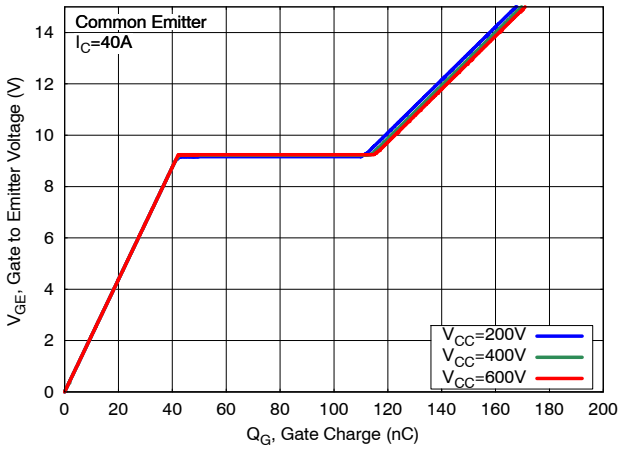


Figure 8. Gate Charge Characteristics

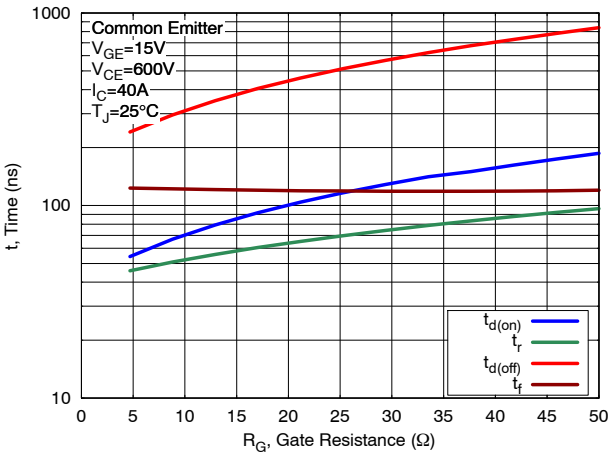


Figure 9. Switching Time vs Gate Resistance

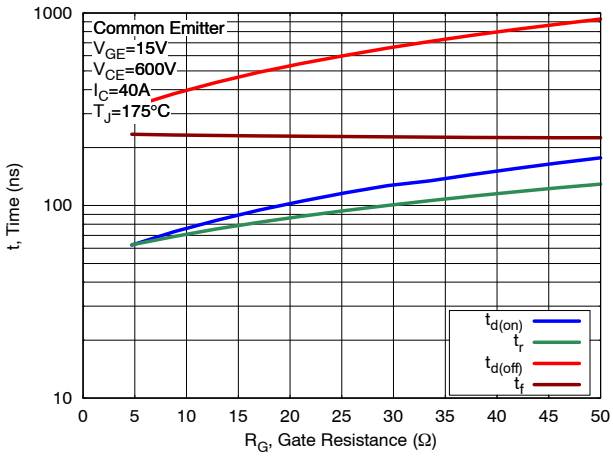


Figure 10. Switching Time vs Gate Resistance

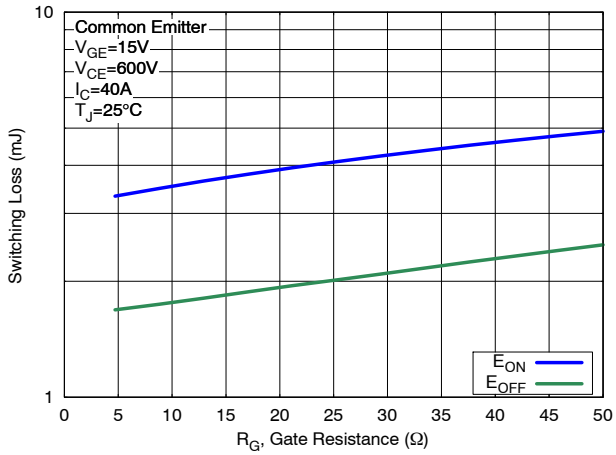


Figure 11. Switching Loss vs Gate Resistance

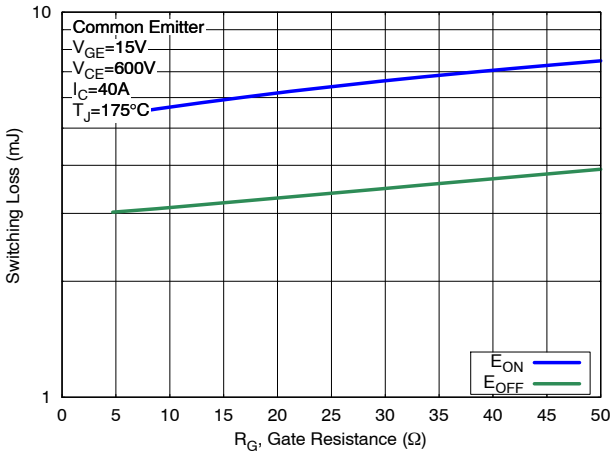


Figure 12. Switching Loss vs Gate Resistance

Share Feedback
Your Opinion Matters

TYPICAL CHARACTERISTICS

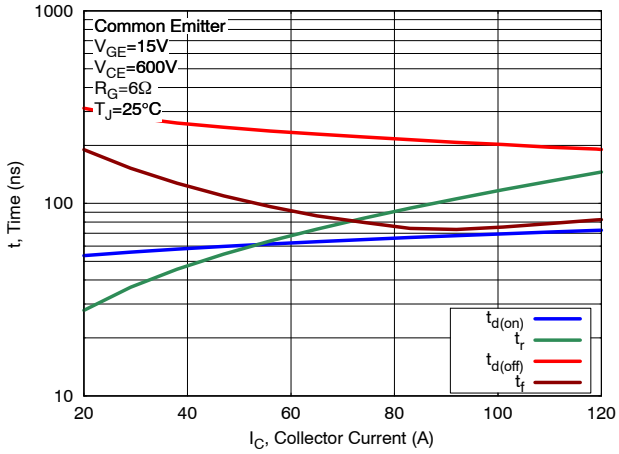


Figure 13. Switching Time vs Collector Current

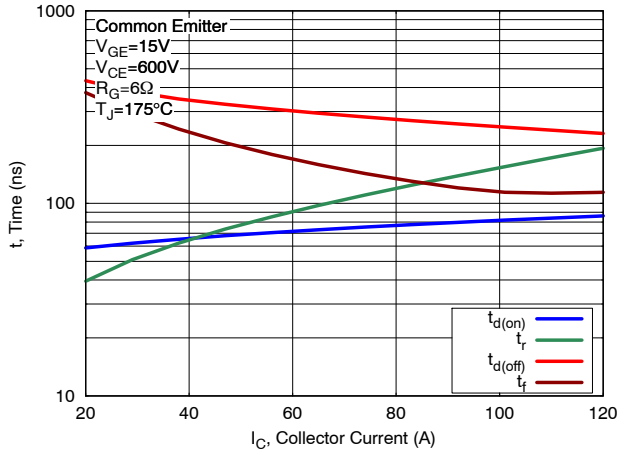


Figure 14. Switching Time vs Collector Current

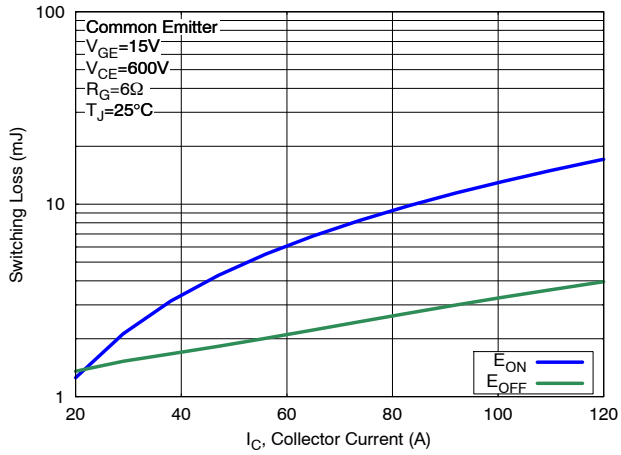


Figure 15. Switching Loss vs Collector Current

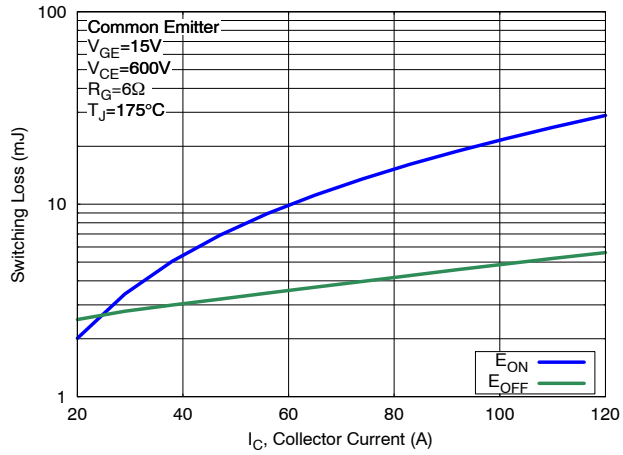


Figure 16. Switching Loss vs Collector Current

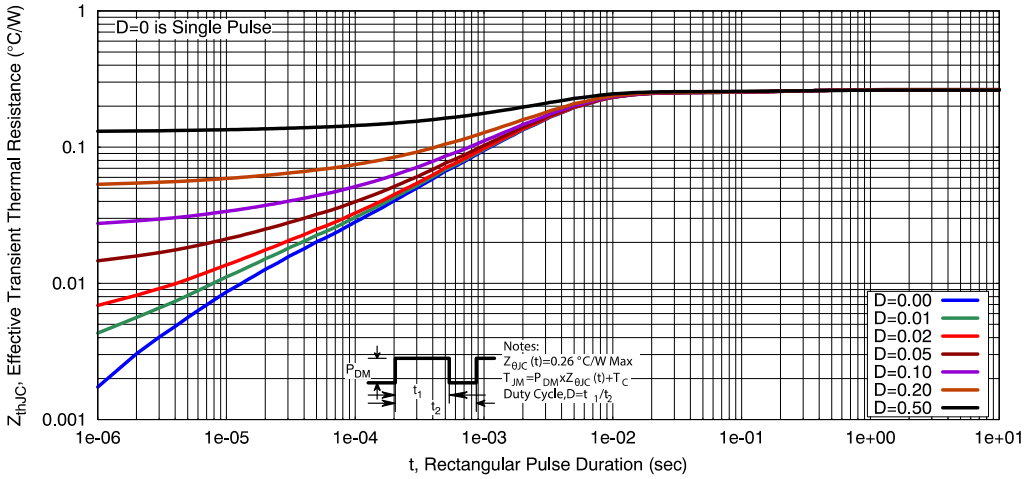
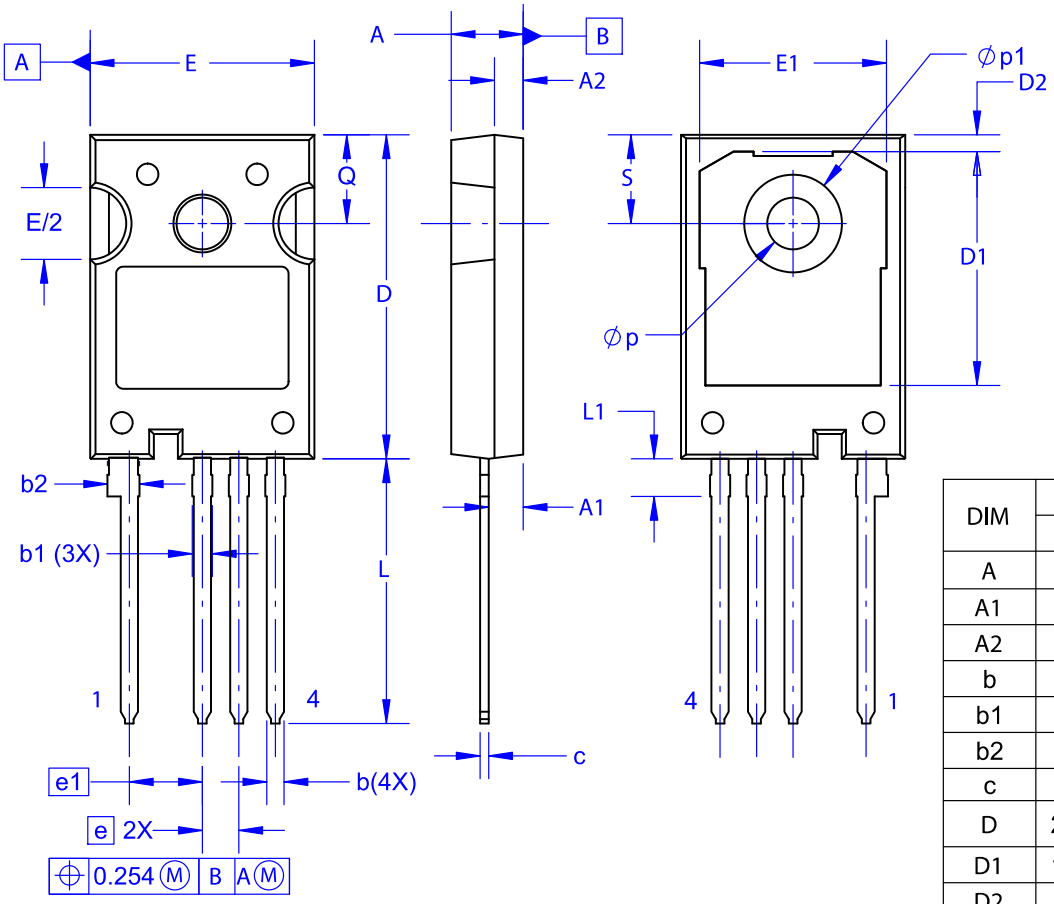


Figure 17. Transient Thermal Impedance of IGBT

Share Feedback
Your Opinion Matters

TO−247−4LD
CASE 340CJ
ISSUE A

DATE 16 SEP 2019



DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.10	2.40	2.70
A2	1.80	2.00	2.20
b	1.07	1.20	1.33
b1	1.20	1.40	1.60
b2	2.02	2.22	2.42
c	0.50	0.60	0.70
D	22.34	22.54	22.74
D1	16.00	16.25	16.50
D2	0.97	1.17	1.37
e	2.54 BSC		
e1	5.08 BSC		
E	15.40	15.60	15.80
E1	12.80	13.00	13.20
E/2	4.80	5.00	5.20
L	18.22	18.42	18.62
L1	2.42	2.62	2.82
p	3.40	3.60	3.80
p1	6.60	6.80	7.00
Q	5.97	6.17	6.37
S	5.97	6.17	6.37

NOTES:

A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
B. DIMENSIONS ARE EXCLUSIVE OF BURRS,MOLD FLASH,AND TIE BAR EXTRUSIONS.
C. ALL DIMENSIONS ARE IN MILLIMETERS.
D. DRAWING CONFORMS TO ASME Y14.5-2009.

DOCUMENT NUMBER:	**98AON13852G**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	**TO−247−4LD**	**PAGE 1 OF 1**

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba **onsemi** or its subsidiaries in the United States and/or other countries. **onsemi** reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.

onsemi, onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent−Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as−is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:
Technical Library: www.onsemi.com/design/resources/technical−documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support
For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales